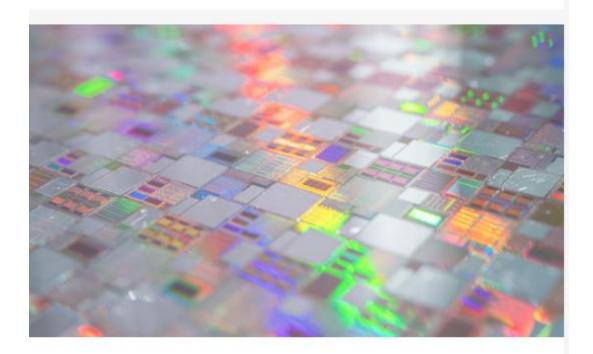


EV Group Hybrid Bonding and Nanoimprint Lithography Solutions to be Highlighted at SEMICON Taiwan 2023 – September 1, 2023





Keeping Semiconductor Supply Chains Flowing in a World of Change

The COVID-19 pandemic exposed the complexity and fragility of our global supply network, highlighting the importance of resilient semiconductor supply chains and the need for strategic inventory management systems. Effective inventory management is critical to maintain a competitive edge in today's fast-paced business environment. But how do you achieve that?

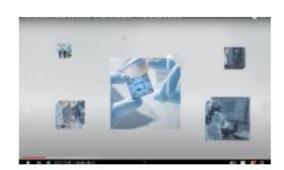




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Multi-purpose Manual Die Bonder for Lab & Research Winbond Electronics' Alex Wei and Omar Ma Talk About the Memory of Everything

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SIEMENS

As the pace of innovation in electronics constantly accelerates, Siemens EDA is committed to delivering the world's most comprehensive portfolio of electronic design automation (EDA) software, hardware, and services to enable customers to deliver life-changing innovations faster and become market leaders. Siemens EDA, a segment of Siemens Digital Industries Software, is a technology leader in software and hardware for electronic design automation (EDA). Siemens EDA offers proven software tools and industry-leading technology to address the challenges of design and system-level scaling, delivering more predictable outcomes when transitioning to the next technology node. With a closed-loop digital twin managing the silicon lifecycle, data can move freely between design, manufacturing, and the cloud for chips, boards, and electrical and electronic systems. The company is currently hiring.

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Community News

Events Calendar

PulseForge and Applied Novel Devices
Collaborate to Showcase Breakthrough
in Photonic Debonding for Advanced
Power Electronics Packaging

European Packaging, Assembly, and Test – Workshop 2023 Sep 6, 2023 Brewer Science Unveils Innovative
Advanced Packaging Solutions at
SEMICON Taiwan and Advanced
Packaging Summit 2023

EV Group Hybrid Bonding and Nanoimprint Lithography Solutions to be Highlighted at SEMICON Taiwan 2023

Nordson TEST & INSPECTION
Showcases State-of-the-art Inspection
and Metrology Solutions at SEMICON
Taiwan

Recommended Reads

Global 'Chips Acts' Open Debate About Best Way Forward – EE Times

Automotive Complexity, Supply Chain Strength Demands Tech Collaboration -SemiEngineering 34th Annual Electronics Packaging Symposium Sep 6, 2023

SEMICON Taiwan 2023

Sep 6, 2023

Road to Chiplets - Ecosystems 2023 Sep. 13, 2023

Webinar: SEMI License Server Certification Protocol Sep. 26, 2023

IMAPS 2023 San Diego Oct. 2-5, 2023

Bridging the Gender Gap Through
Allyship

Nov. 7, 2023

SEMICON Europa 2023

Nov. 15-18, 2023

